

1. Disassembly Procedures

**S1** Turn off the monitor.

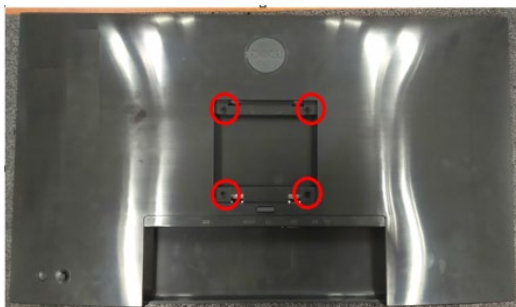
**S2** To remove the stand  
 1. Place the monitor on a soft cloth or cushion

2. Press and hold the stand release button at the back of the display

3. Lift the stand assembly up and away from the monitor

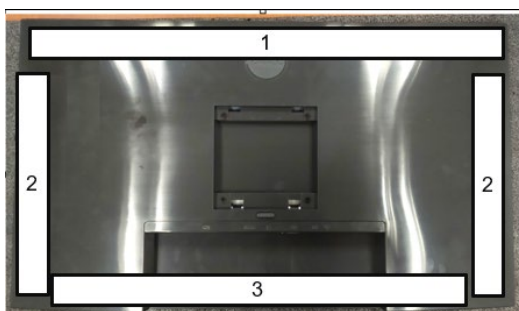


**S3** Unlock 4 screws on "Rear Cover"

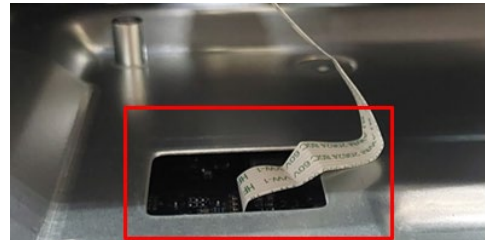


(Screw Torque: 9±1 kgf)

**S4** Use hands or "Bar Scraper" to disassemble "Rear Cover" from "Middle Frame" according to the sequence shown in the picture

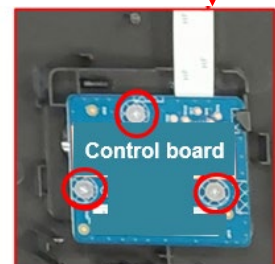
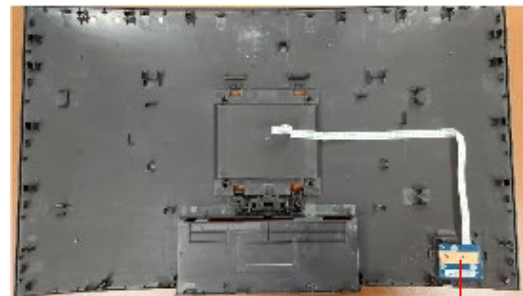


**S5** Pull out "Control board FFC" from "Interface board" and tear off it from "Main Shielding" to take off "Rear Cover"



**S6** Unlock 3 screws to disassemble "Control board" from "Rear Cover"

Tear off "Control board FFC" from "Rear Cover" and take off "Control board" from "Rear Cover"

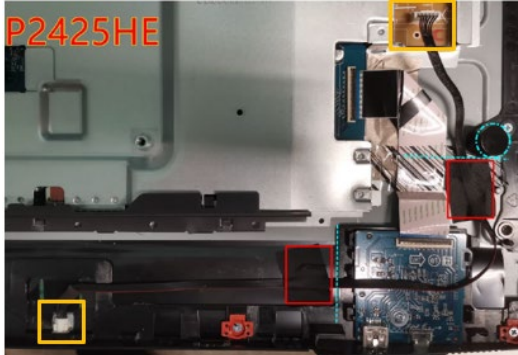


(Screw Torque: 1.6-1.8 kgf)

**S7** Disassemble "Control board FFC" from "Control board"



- S8** Tear off 2 tapes from “Backlight wire”  
Unplug “Backlight wire” from “LED Driver board” and “Panel”

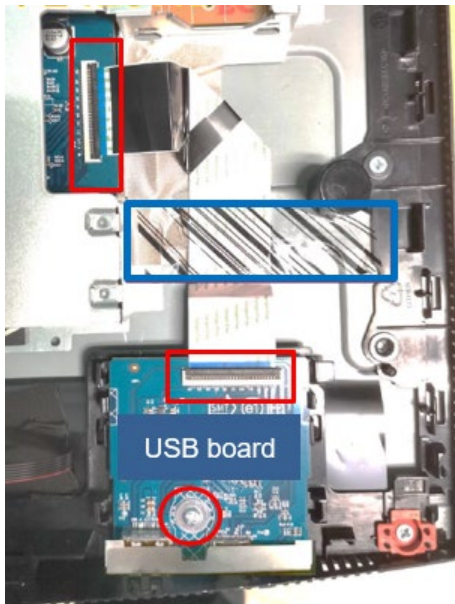


- S9** Tear off a black tape from “USB board FFC” and “Panel”

Disassemble “USB board FFC” from “USB board” and “Interface board”

Unlock 1 screw on “USB board”

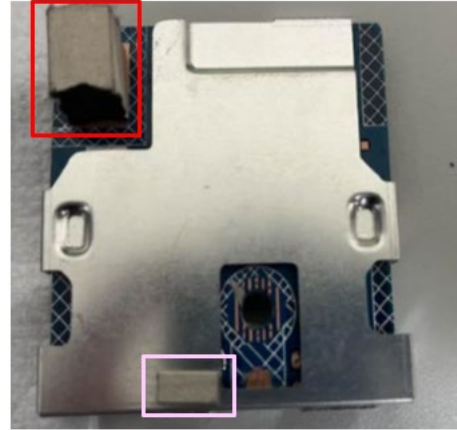
Disassemble “USB board” from “Middle Frame”



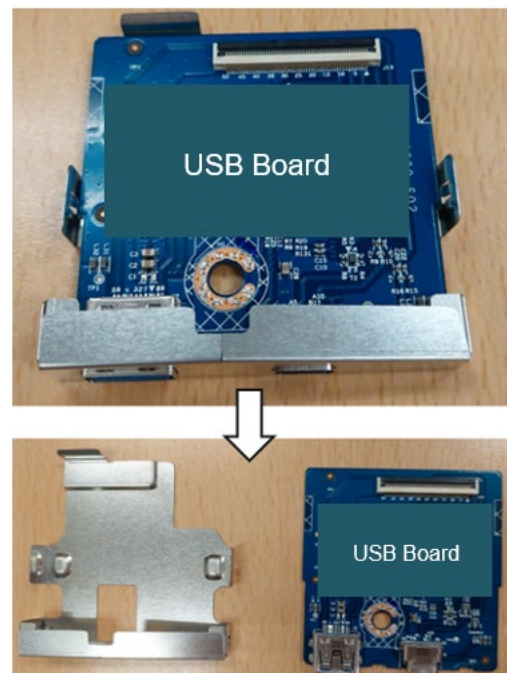
(Screw Torque: 4.5±0.5 kgf)

- S10** Tear off a gasket from “USB Shielding” (see pink mark)

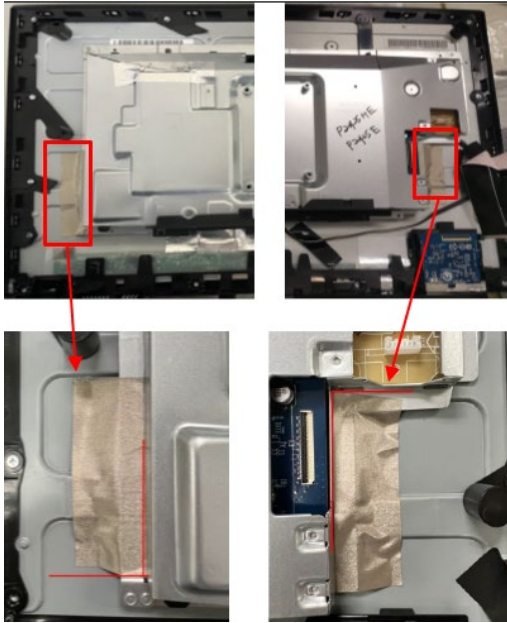
Tear off a gasket from “USB board” (see red mark)



- S11** Disassemble “USB board” from “USB Shielding”



- S12** Tear off 2 conductive tapes from “Main Shielding” and “Panel”



- S13** Tear off an aluminum foil and a yellow tape from “LVDS FFC” on “Panel”



- S14** Disassemble “LVDS FFC” from “Panel”  
Take off “Main Shielding” from “Panel”



- S15** Unlock 13 screws to disassemble “Middle Frame” from “Panel”

Take off “Middle Frame” from “Panel”

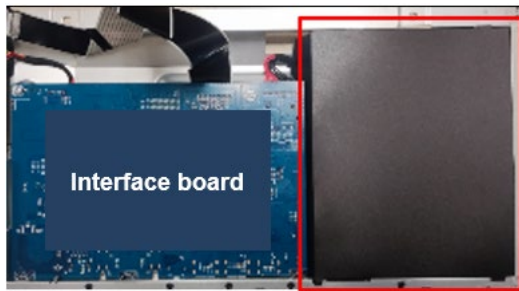


(Screw Torque: 4.5-5.0 kgf)

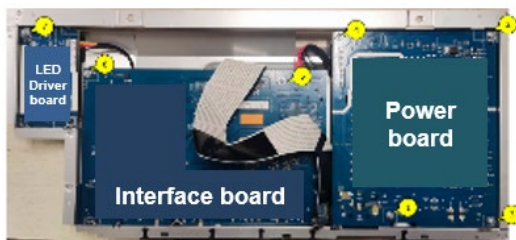
- S16** Tear off two acetate tapes from the convex holes on “Panel”



- S17** Disassemble “MYLAR” from “Main Shielding”



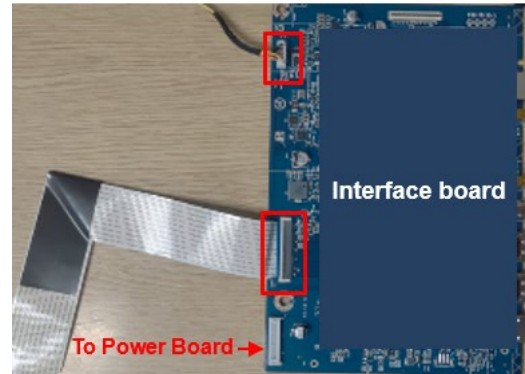
- S18** Unlock 7 PCBA screws



(Screw Torque:  $9\pm 1$  kgf)

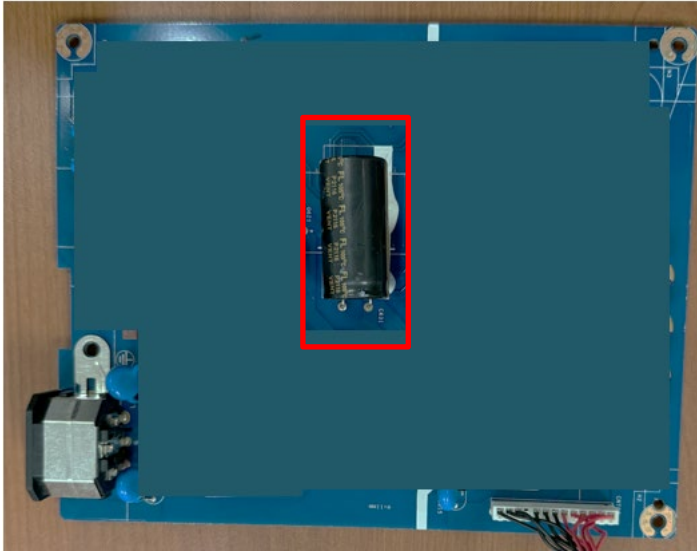
- S19** Disassemble “LED Driver board”, “Interface board” and “Power board” from “Main Shielding”

Unplug all cables from “Interface board”

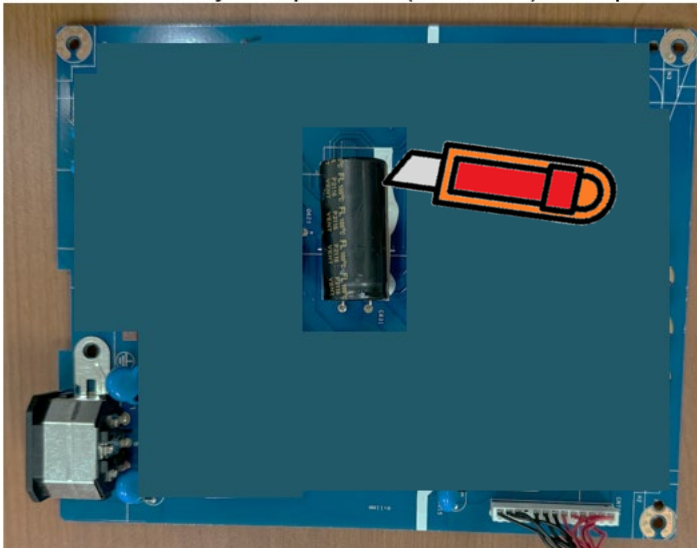




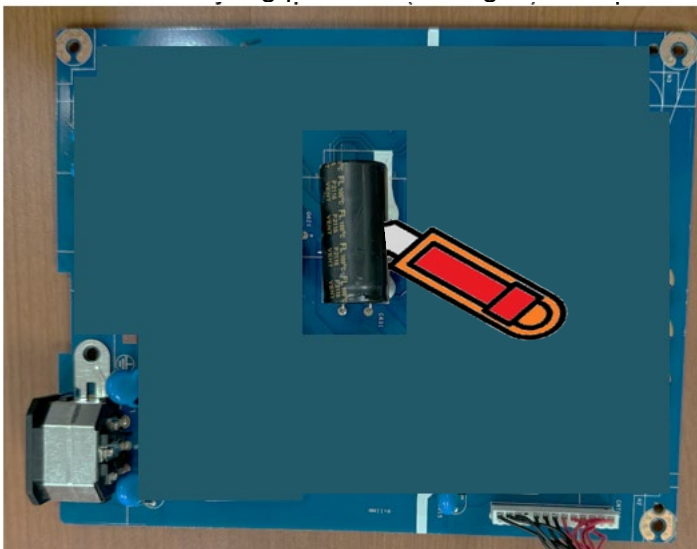
**S20** Remove electrolyte capacitors (red mark) from printed circuit boards



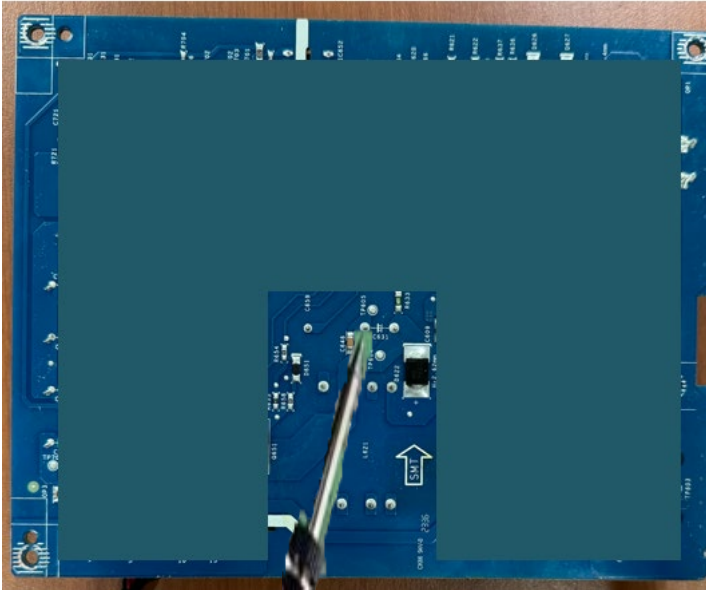
S20-1 Cut the glue between bulk cap. and PCB with a knife



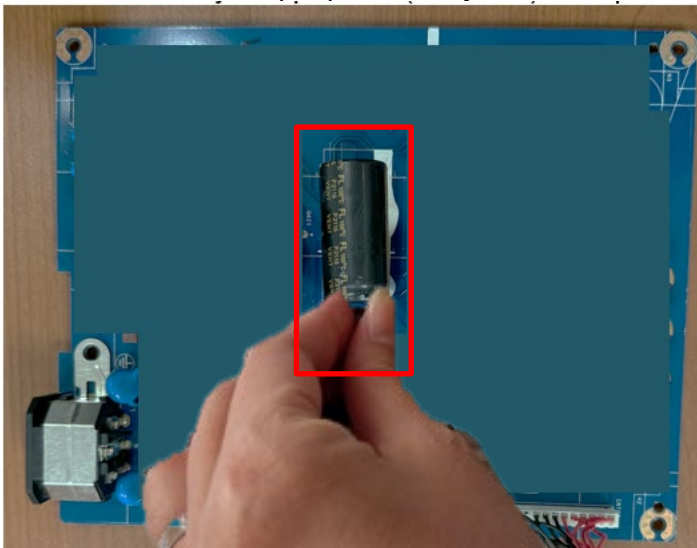
S20-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S20-3 Take out bulk cap. pin solder with soldering iron and absorber



S20-4 Lift the bulk cap. up and away from the PCB



## 2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater than 10 square cm)	Product has printed circuit boards (with a surface greater than 10 square cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and HC	No used
Gas discharge lamps	No used
LCD display > 100 cm <sup>2</sup>	Product has an LCD greater than 100 cm <sup>2</sup>
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Product has electrolyte capacitors (height >25mm, diameter > 25mm)

## 3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber